

AMP 4805 REV 31MAR2000

LOC		DIST		REVISIONS			
AA		22		P	LTR	DESCRIPTION	DATE
				A		ECOS11-0204-04	14APR2005

- 1

DATUM AND BASIC DIMENSION ESTABLISHED BY CUSTOMER.
- 2

RECOMMENDED PC BOARD THICKNESS IS 2.36[.093].)
- 3

RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F

4. MATERIAL:

HOUSING: PLASTIC HOUSINGS: UL94V-0/5V THERMOPLASTIC. SEE TABLE FOR COLOR.

TERMINAL: USB: 0.251±0.013 THICK PHOSPHOR BRONZE PLATED WITH 1.27µm NICKEL. IN LOCALIZED GOLD PLATE AREA 0.076µm MIN GOLD OVER 0.76µm MIN PALLADIUM-NICKEL IS ADDED OVER NICKEL UNDERPLATE. IN SOLDER AREA 3.8µm MIN TIN IS ADDED OVER NICKEL UNDERPLATE.

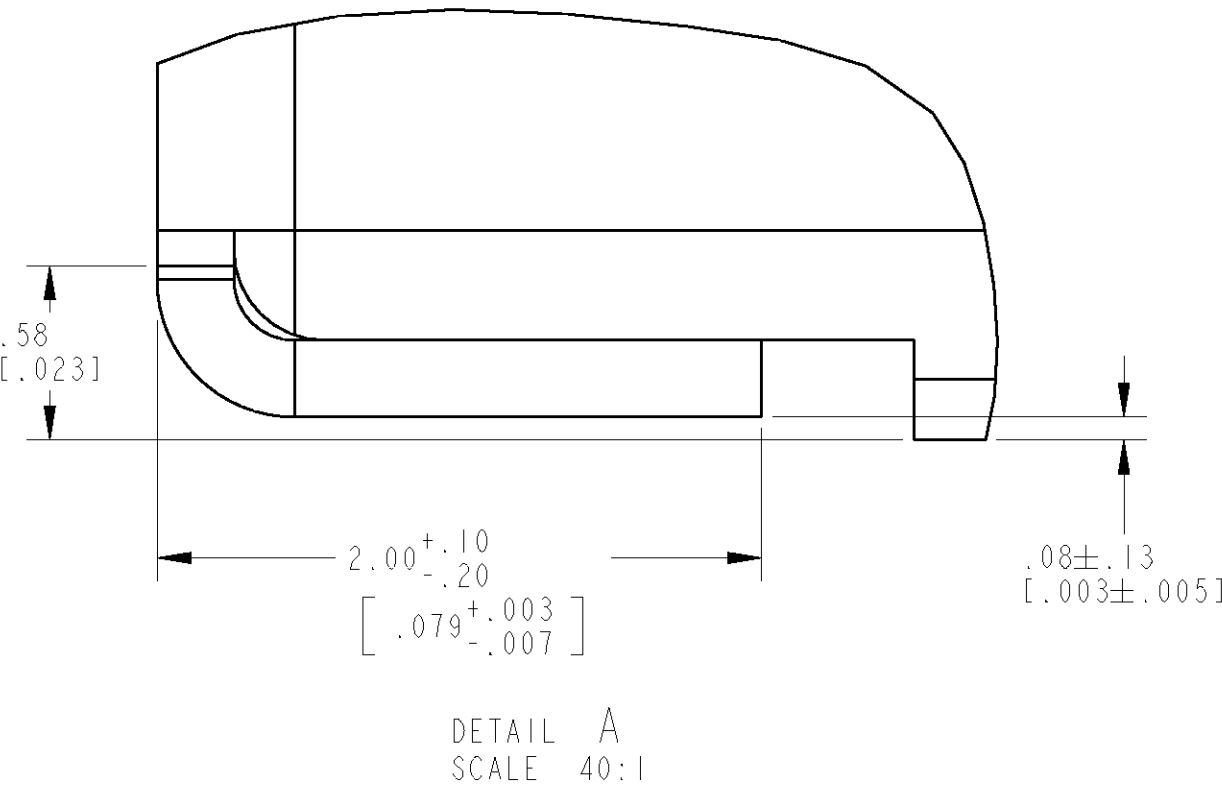
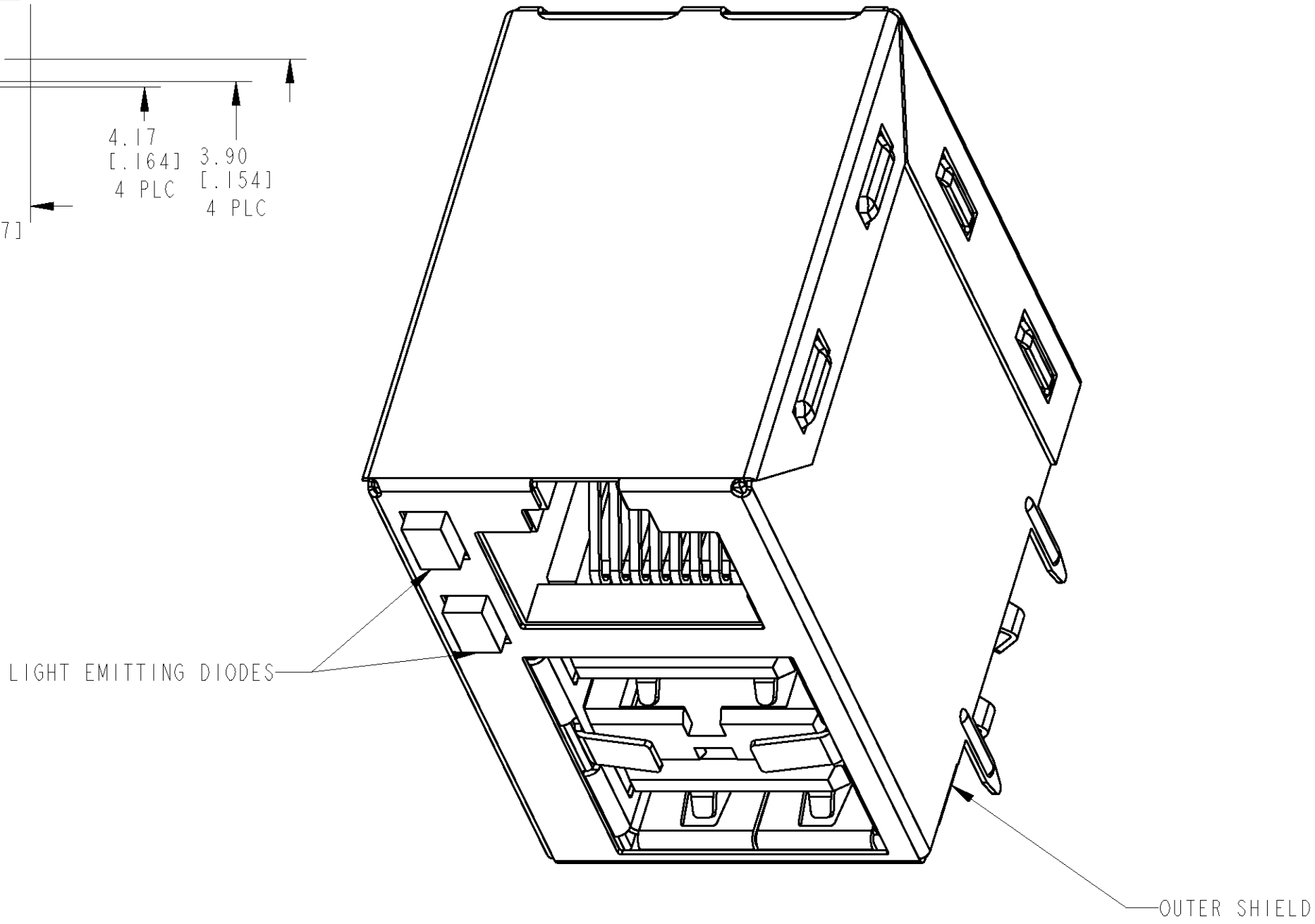
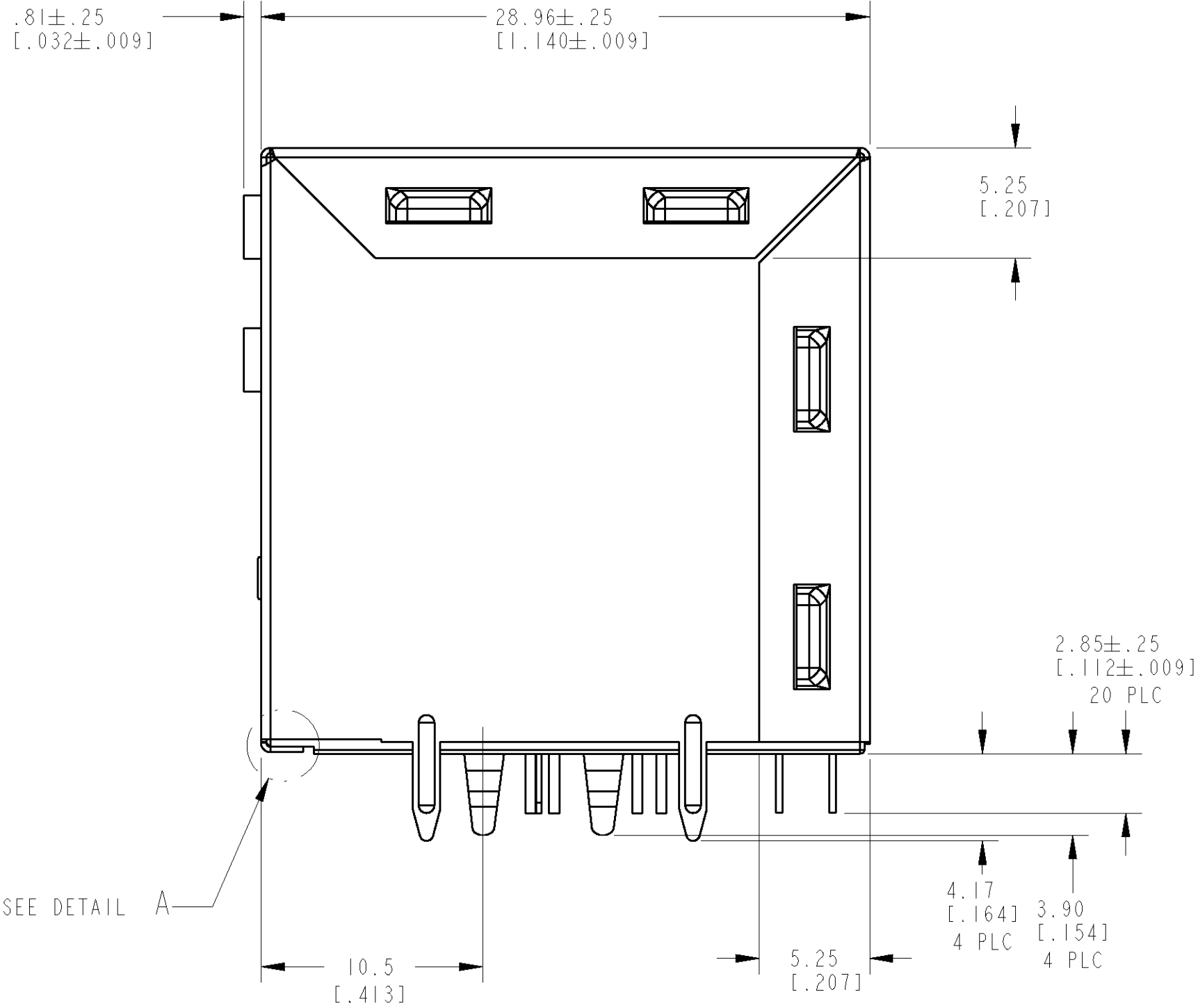
RJ45: 0.318 THICK PHOSPHOR BRONZE PLATED WITH 1.27µm MIN THICK NICKEL. IN LOCALIZED GOLD PLATE AREA 1.27µm MIN THICK GOLD IS ADDED OVER NICKEL UNDERPLATE. IN SOLDER AREA 3.8µm MIN TIN IS ADDED OVER NICKEL UNDERPLATE.

LED: 0.5 DIAMETER CARBON STEEL LEADS PREPLATED WITH 8.89 µm THICK Sn/Cu, OVER 2.03 µm THICK Ag, OVER 1.02 µm THICK Cu, OVER 3.56 µm THICK Ni, OVER 1.02 µm Cu UNDERPLATE

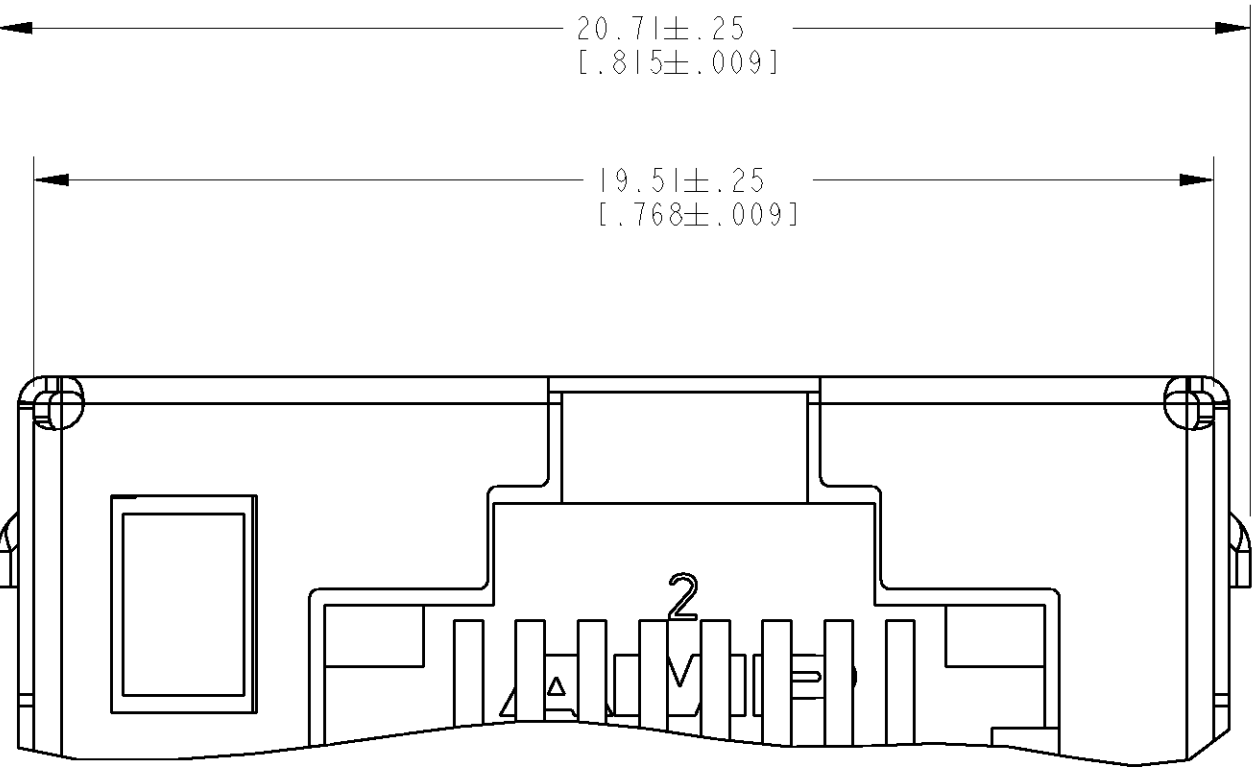
SHIELD: OUTER: 0.254 THICK COPPER-ZINC ALLOY PREPLATED WITH TIN 2µm TO 3.8µm THICK

INNER: 0.318 THICK COPPER-ZINC ALLOY PREPLATED WITH TIN 2µm TO 3.8µm THICK

USB: 0.318 THICK PHOSPHOR-BRONZE PREPLATED WITH 5.1µm MIN TIN



DETAIL A
SCALE 40:1



DETAIL B
SCALE 8:1

WITH LEDS		6116640-1	
DESCRIPTION		PART NO.	
J. GERACE/L. A. MAYER		AMP Incorporated	
J. WESTMAN		Harrisburg, PA 17105-3608	
S. FLICKINGER		ASSEMBLY, RJ-45 MODULAR JACK OVER STACKED USB RECEPTACLE	
PRODUCT SPEC		-	
APPLICATION SPEC		-	
WEIGHT		-	
CUSTOMER DRAWING		-	
SCALE		4:1	
SHEET		1 OF 2	
REV		A	

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[TE Connectivity:](#)

[6116640-1](#)